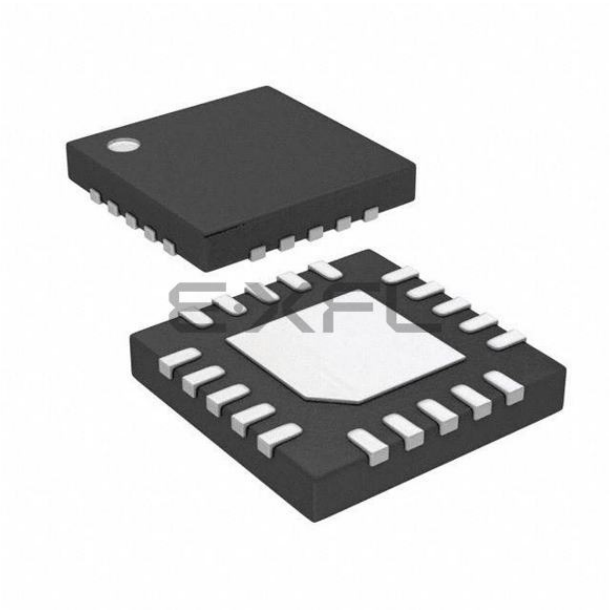

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Applications of "Embedded - Microcontrollers"

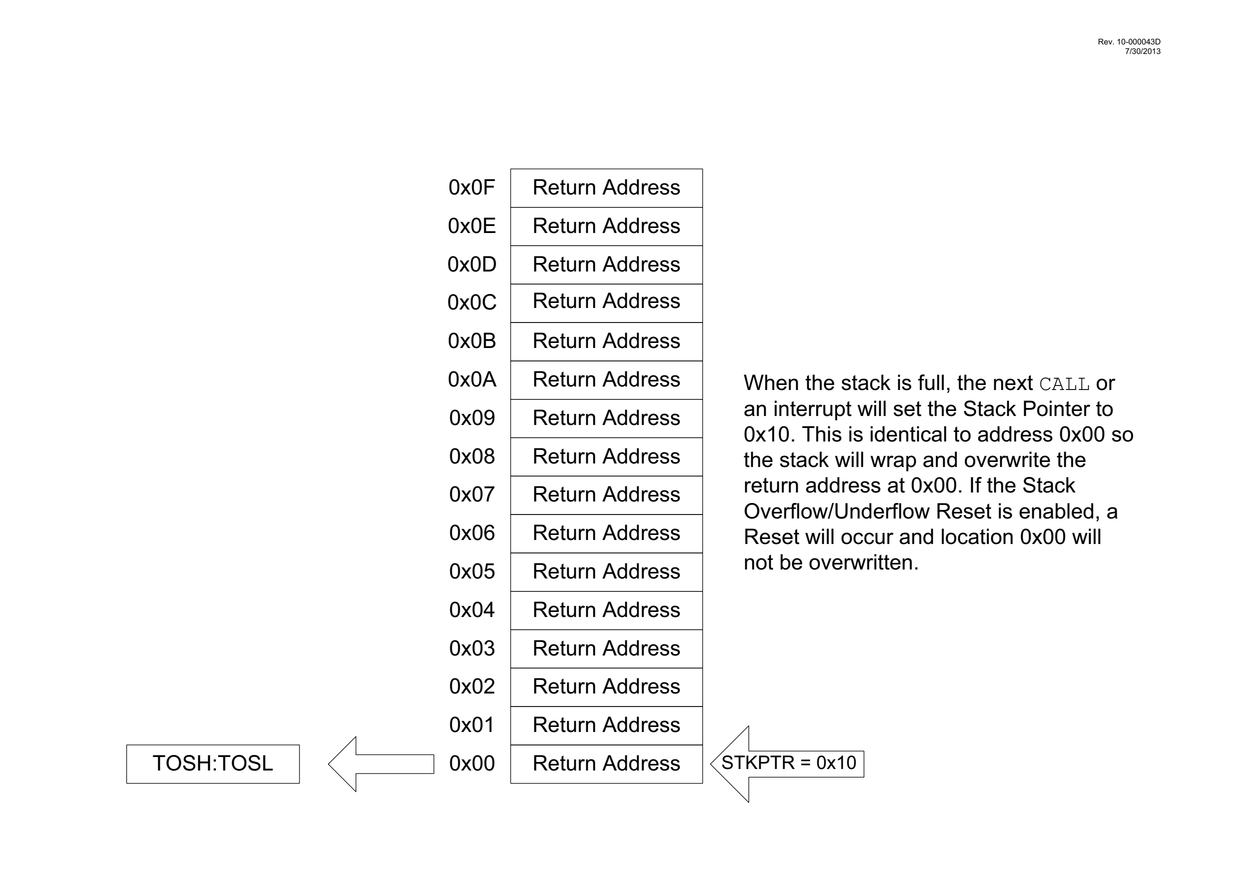
Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	17
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 12x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-UFQFN Exposed Pad
Supplier Device Package	20-UQFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1508t-i-gz

TABLE 3-4: PIC16(L)F1509 MEMORY MAP, BANK 0-7

Address	BANK 0	Address	BANK 1	Address	BANK 2	Address	BANK 3	Address	BANK 4	Address	BANK 5	Address	BANK 6	Address	BANK 7
000h–00Bh	Core Registers (Table 3-2)	080h–08Bh	Core Registers (Table 3-2)	100h–10Bh	Core Registers (Table 3-2)	180h–18Bh	Core Registers (Table 3-2)	200h–20Bh	Core Registers (Table 3-2)	280h–28Bh	Core Registers (Table 3-2)	300h–30Bh	Core Registers (Table 3-2)	380h–38Bh	Core Registers (Table 3-2)
00Ch	PORTA	08Ch	TRISA	10Ch	LATA	18Ch	ANSELA	20Ch	WPUA	28Ch	—	30Ch	—	38Ch	—
00Dh	PORTB	08Dh	TRISB	10Dh	LATB	18Dh	ANSELB	20Dh	WPUB	28Dh	—	30Dh	—	38Dh	—
00Eh	PORTC	08Eh	TRISC	10Eh	LATC	18Eh	ANSELC	20Eh	—	28Eh	—	30Eh	—	38Eh	—
00Fh	—	08Fh	—	10Fh	—	18Fh	—	20Fh	—	28Fh	—	30Fh	—	38Fh	—
010h	—	090h	—	110h	—	190h	—	210h	—	290h	—	310h	—	390h	—
011h	PIR1	091h	PIE1	111h	CM1CON0	191h	PMADRL	211h	SSP1BUF	291h	—	311h	—	391h	IOCAP
012h	PIR2	092h	PIE2	112h	CM1CON1	192h	PMADRH	212h	SSP1ADD	292h	—	312h	—	392h	IOCAN
013h	PIR3	093h	PIE3	113h	CM2CON0	193h	PMDATL	213h	SSP1MSK	293h	—	313h	—	393h	IOCAF
014h	—	094h	—	114h	CM2CON1	194h	PMDATH	214h	SSP1STAT	294h	—	314h	—	394h	IOCBP
015h	TMR0	095h	OPTION_REG	115h	CMOUT	195h	PMCON1	215h	SSP1CON1	295h	—	315h	—	395h	IOCBN
016h	TMR1L	096h	PCON	116h	BORCON	196h	PMCON2	216h	SSP1CON2	296h	—	316h	—	396h	IOCBF
017h	TMR1H	097h	WDTCON	117h	FVRCON	197h	VREGCON	217h	SSP1CON3	297h	—	317h	—	397h	—
018h	T1CON	098h	—	118h	DAC1CON0	198h	—	218h	—	298h	—	318h	—	398h	—
019h	T1GCON	099h	OSCCON	119h	DAC1CON1	199h	RCREG	219h	—	299h	—	319h	—	399h	—
01Ah	TMR2	09Ah	OSCSTAT	11Ah	—	19Ah	TXREG	21Ah	—	29Ah	—	31Ah	—	39Ah	—
01Bh	PR2	09Bh	ADRESL	11Bh	—	19Bh	SPBRG	21Bh	—	29Bh	—	31Bh	—	39Bh	—
01Ch	T2CON	09Ch	ADRESH	11Ch	—	19Ch	SPBRGH	21Ch	—	29Ch	—	31Ch	—	39Ch	—
01Dh	—	09Dh	ADCON0	11Dh	APFCON	19Dh	RCSTA	21Dh	—	29Dh	—	31Dh	—	39Dh	—
01Eh	—	09Eh	ADCON1	11Eh	—	19Eh	TXSTA	21Eh	—	29Eh	—	31Eh	—	39Eh	—
01Fh	—	09Fh	ADCON2	11Fh	—	19Fh	BAUDCON	21Fh	—	29Fh	—	31Fh	—	39Fh	—
020h–06Fh	General Purpose Register 80 Bytes	0A0h–0EFh	General Purpose Register 80 Bytes	120h–16Fh	General Purpose Register 80 Bytes	1A0h–1EFh	General Purpose Register 80 Bytes	220h–26Fh	General Purpose Register 80 Bytes	2A0h–2EFh	General Purpose Register 80 Bytes	320h–36Fh	General Purpose Register 16Bytes; Unimplemented Read as '0'	3A0h–3EFh	Unimplemented Read as '0'
070h–07Fh	Common RAM	0F0h–0FFh	Accesses 70h – 7Fh	170h–17Fh	Accesses 70h – 7Fh	1F0h–1FFh	Accesses 70h – 7Fh	270h–27Fh	Accesses 70h – 7Fh	2F0h–2FFh	Accesses 70h – 7Fh	370h–37Fh	Accesses 70h – 7Fh	3F0h–3FFh	Accesses 70h – 7Fh

Legend: (shaded) = Unimplemented data memory locations, read as '0'.

FIGURE 3-7: ACCESSING THE STACK EXAMPLE 4



3.5.2 OVERFLOW/UNDERFLOW RESET

If the STVREN bit in Configuration Words is programmed to '1', the device will be reset if the stack is PUSHed beyond the sixteenth level or POPed beyond the first level, setting the appropriate bits (STKOVF or STKUNF, respectively) in the PCON register.

3.6 Indirect Addressing

The INDFn registers are not physical registers. Any instruction that accesses an INDFn register actually accesses the register at the address specified by the File Select Registers (FSR). If the FSRn address specifies one of the two INDFn registers, the read will return '0' and the write will not occur (though Status bits may be affected). The FSRn register value is created by the pair FSRnH and FSRnL.

The FSR registers form a 16-bit address that allows an addressing space with 65536 locations. These locations are divided into three memory regions:

- Traditional Data Memory
- Linear Data Memory
- Program Flash Memory

5.2 Clock Source Types

Clock sources can be classified as external, internal or peripheral.

External clock sources rely on external circuitry for the clock source to function. Examples are: oscillator modules (ECH, ECM, ECL modes), quartz crystal resonators or ceramic resonators (LP, XT and HS modes) and Resistor-Capacitor (EXTRC) mode circuits.

Internal clock sources are contained within the oscillator module. The internal oscillator block has two internal oscillators that are used to generate the internal system clock sources: the 16 MHz High-Frequency Internal Oscillator (HFINTOSC) and the 31 kHz Low-Frequency Internal Oscillator (LFINTOSC).

The peripheral clock source is a nominal 600 kHz internal RC oscillator, FRC. The FRC is traditionally used with the ADC module, but is sometimes available to other peripherals. See **Section 5.2.2.4 “Peripheral Clock Sources”**.

The system clock can be selected between external or internal clock sources via the System Clock Select (SCS) bits in the OSCCON register. See **Section 5.3 “Clock Switching”** for additional information.

5.2.1 EXTERNAL CLOCK SOURCES

An external clock source can be used as the device system clock by performing one of the following actions:

- Program the FOSC<2:0> bits in the Configuration Words to select an external clock source that will be used as the default system clock upon a device Reset.
- Write the SCS<1:0> bits in the OSCCON register to switch the system clock source to:
  - Secondary oscillator during run-time, or
  - An external clock source determined by the value of the FOSC bits.

See **Section 5.3 “Clock Switching”** for more information.

5.2.1.1 EC Mode

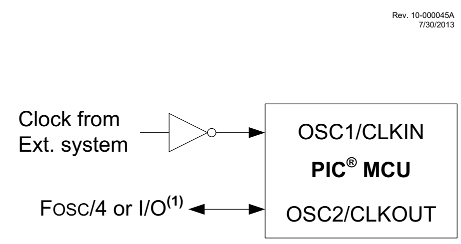
The External Clock (EC) mode allows an externally generated logic level signal to be the system clock source. When operating in this mode, an external clock source is connected to the OSC1 input. OSC2/CLKOUT is available for general purpose I/O or CLKOUT. Figure 5-2 shows the pin connections for EC mode.

EC mode has three power modes to select from through the FOSC bits in the Configuration Words:

- ECH – High-power, 4-20 MHz
- ECM – Medium-power, 0.5-4 MHz
- ECL – Low-power, 0-0.5 MHz

The Oscillator Start-up Timer (OST) is disabled when EC mode is selected. Therefore, there is no delay in operation after a Power-on Reset (POR) or wake-up from Sleep. Because the PIC® MCU design is fully static, stopping the external clock input will have the effect of halting the device while leaving all data intact. Upon restarting the external clock, the device will resume operation as if no time had elapsed.

FIGURE 5-2: EXTERNAL CLOCK (EC) MODE OPERATION



Note 1: Output depends upon the $\overline{\text{CLKOUTEN}}$ bit of the Configuration Words.

5.2.1.2 LP, XT, HS Modes

The LP, XT and HS modes support the use of quartz crystal resonators or ceramic resonators connected to OSC1 and OSC2 (Figure 5-3). The three modes select a low, medium or high gain setting of the internal inverter-amplifier to support various resonator types and speed.

LP Oscillator mode selects the lowest gain setting of the internal inverter-amplifier. LP mode current consumption is the least of the three modes. This mode is designed to drive only 32.768 kHz tuning-fork type crystals (watch crystals).

XT Oscillator mode selects the intermediate gain setting of the internal inverter-amplifier. XT mode current consumption is the medium of the three modes. This mode is best suited to drive resonators with a medium drive level specification.

HS Oscillator mode selects the highest gain setting of the internal inverter-amplifier. HS mode current consumption is the highest of the three modes. This mode is best suited for resonators that require a high drive setting.

Figure 5-3 and Figure 5-4 show typical circuits for quartz crystal and ceramic resonators, respectively.

5.4.1 TWO-SPEED START-UP MODE CONFIGURATION

Two-Speed Start-up mode is configured by the following settings:

- IESO (of the Configuration Words) = `1`; Internal/External Switchover bit (Two-Speed Start-up mode enabled).
- SCS (of the OSCCON register) = `00`.
- FOSC<2:0> bits in the Configuration Words configured for LP, XT or HS mode.

Two-Speed Start-up mode is entered after:

- Power-on Reset (POR) and, if enabled, after Power-up Timer (PWRT) has expired, or
- Wake-up from Sleep.

Note:	When FSCM is enabled, Two-Speed Start-up will automatically be enabled.

5.4.2 TWO-SPEED START-UP SEQUENCE

1. Wake-up from Power-on Reset or Sleep.
2. Instructions begin execution by the internal oscillator at the frequency set in the IRCF<3:0> bits of the OSCCON register.
3. OST enabled to count 1024 clock cycles.
4. OST timed out, wait for falling edge of the internal oscillator.
5. OSTS is set.
6. System clock held low until the next falling edge of new clock (LP, XT or HS mode).
7. System clock is switched to external clock source.

5.4.3 CHECKING TWO-SPEED CLOCK STATUS

Checking the state of the OSTS bit of the OSCSTAT register will confirm if the CPU is running from the external clock source, as defined by the FOSC<2:0> bits in the Configuration Words, or the internal oscillator. See Table 5-2.

TABLE 5-3: OSCILLATOR SWITCHING DELAYS

Switch From	Switch To	Oscillator Delay
Any clock source	LFINTOSC	1 cycle of each clock source
	HFINTOSC	2 μs (approx.)
	ECH, ECM, ECL, EXTRC	2 cycles
	LP, XT, HS	1024 Clock Cycles (OST)
	Secondary Oscillator	1024 Secondary Oscillator Cycles

FIGURE 5-8: TWO-SPEED START-UP

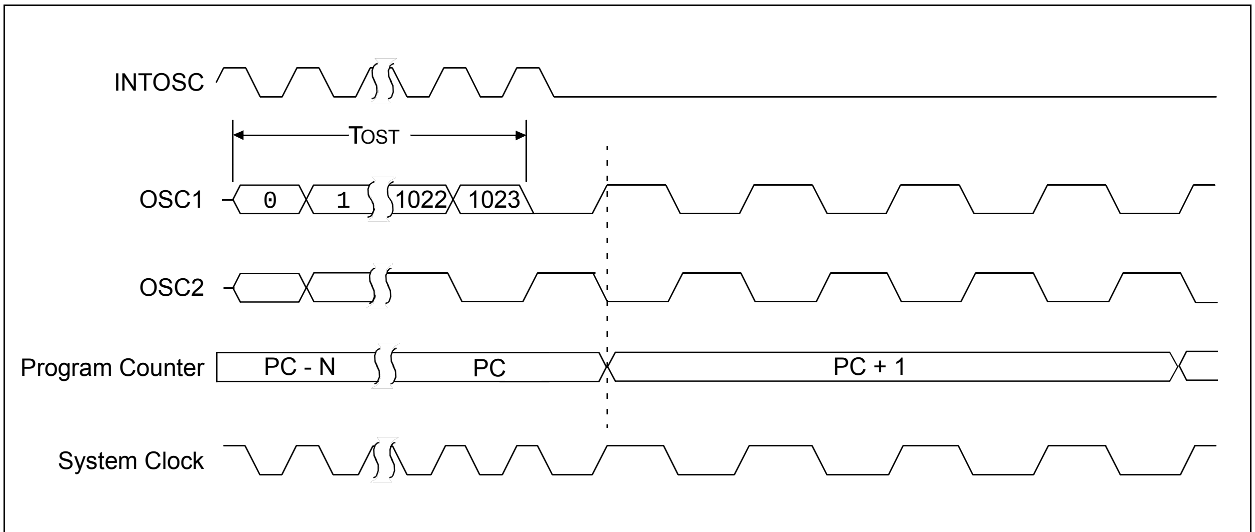
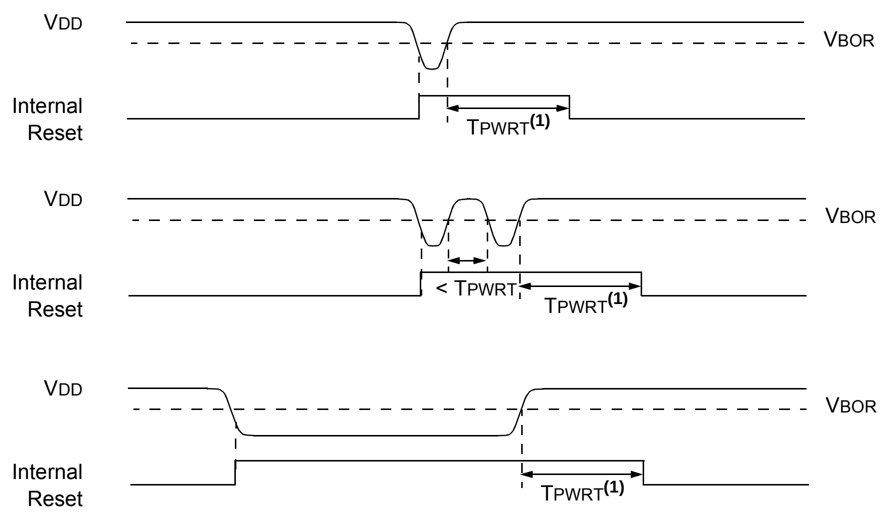


FIGURE 6-2: BROWN-OUT SITUATIONS



Note 1: TPWRT delay only if $\overline{\text{PWRTE}}$ bit is programmed to '0'.

6.3 Register Definitions: BOR Control

REGISTER 6-1: BORCON: BROWN-OUT RESET CONTROL REGISTER

R/W-1/u	R/W-0/u	U-0	U-0	U-0	U-0	U-0	R-q/u
SBOREN	BORFS	—	—	—	—	—	BORRDY
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Value depends on condition

bit 7 **SBOREN:** Software Brown-Out Reset Enable bit
If BOREN <1:0> in Configuration Words = 01:
1 = BOR Enabled
0 = BOR Disabled
If BOREN <1:0> in Configuration Words ≠ 01:
SBOREN is read/write, but has no effect on the BOR

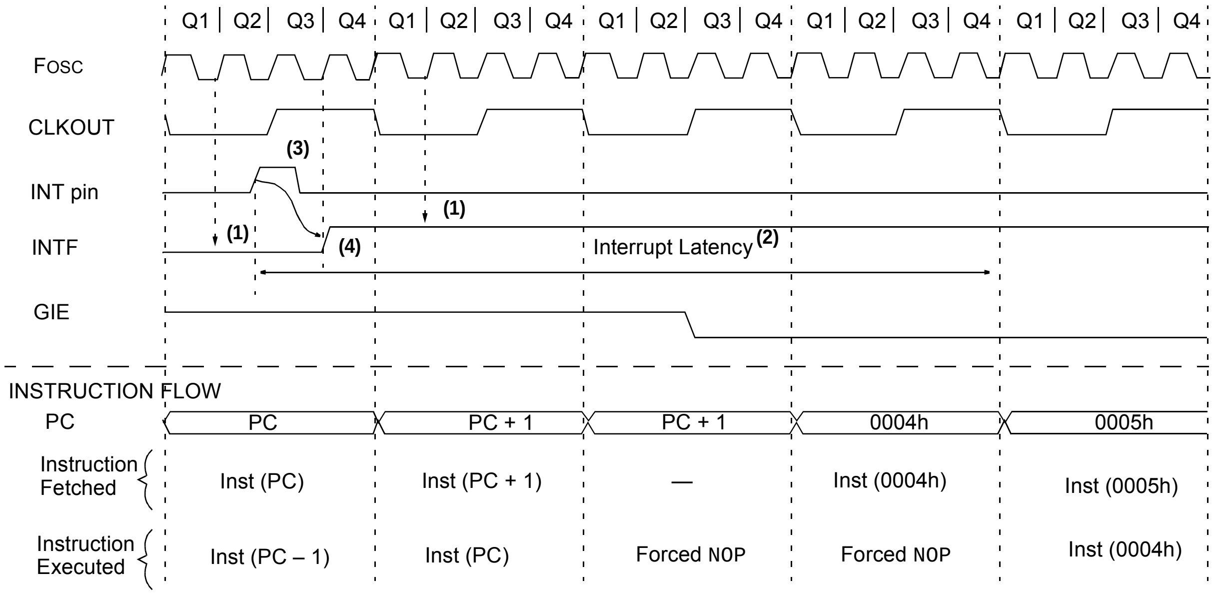
bit 6 **BORFS:** Brown-Out Reset Fast Start bit(1)
If BOREN <1:0> = 10 (Disabled in Sleep) or BOREN<1:0> = 01 (Under software control):
1 = Band gap is forced on always (covers sleep/wake-up/operating cases)
0 = Band gap operates normally, and may turn off
If BOREN<1:0> = 11 (Always on) or BOREN<1:0> = 00 (Always off)
BORFS is Read/Write, but has no effect.

bit 5-1 **Unimplemented:** Read as '0'

bit 0 **BORRDY:** Brown-Out Reset Circuit Ready Status bit
1 = The Brown-out Reset circuit is active
0 = The Brown-out Reset circuit is inactive

Note 1: BOREN<1:0> bits are located in Configuration Words.

FIGURE 7-3: INT PIN INTERRUPT TIMING



Note 1: INTF flag is sampled here (every Q1).

2: Asynchronous interrupt latency = 3-5 TCY. Synchronous latency = 3-4 TCY, where TCY = instruction cycle time. Latency is the same whether Inst (PC) is a single cycle or a 2-cycle instruction.

3: For minimum width of INT pulse, refer to AC specifications in **Section 29.0 “Electrical Specifications”**.

4: INTF is enabled to be set any time during the Q4-Q1 cycles.

REGISTER 10-5: PMCON1: PROGRAM MEMORY CONTROL 1 REGISTER

U-1	R/W-0/0	R/W-0/0	R/W/HC-0/0	R/W/HC-x/q(2)	R/W-0/0	R/S/HC-0/0	R/S/HC-0/0
—(1)	CFGS	LWLO	FREE	WRERR	WREN	WR	RD
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
S = Bit can only be set	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	HC = Bit is cleared by hardware

bit 7 **Unimplemented:** Read as ‘1’

bit 6 **CFGS:** Configuration Select bit
1 = Access Configuration, User ID and Device ID Registers
0 = Access Flash program memory

bit 5 **LWLO:** Load Write Latches Only bit(3)
1 = Only the addressed program memory write latch is loaded/updated on the next WR command
0 = The addressed program memory write latch is loaded/updated and a write of all program memory write latches will be initiated on the next WR command

bit 4 **FREE:** Program Flash Erase Enable bit
1 = Performs an erase operation on the next WR command (hardware cleared upon completion)
0 = Performs a write operation on the next WR command

bit 3 **WRERR:** Program/Erase Error Flag bit
1 = Condition indicates an improper program or erase sequence attempt or termination (bit is set automatically on any set attempt (write ‘1’) of the WR bit).
0 = The program or erase operation completed normally.

bit 2 **WREN:** Program/Erase Enable bit
1 = Allows program/erase cycles
0 = Inhibits programming/erasing of program Flash

bit 1 **WR:** Write Control bit
1 = Initiates a program Flash program/erase operation.
The operation is self-timed and the bit is cleared by hardware once operation is complete.
The WR bit can only be set (not cleared) in software.
0 = Program/erase operation to the Flash is complete and inactive.

bit 0 **RD:** Read Control bit
1 = Initiates a program Flash read. Read takes one cycle. RD is cleared in hardware. The RD bit can only be set (not cleared) in software.
0 = Does not initiate a program Flash read.

Note 1: Unimplemented bit, read as ‘1’.
2: The WRERR bit is automatically set by hardware when a program memory write or erase operation is started (WR = 1).
3: The LWLO bit is ignored during a program memory erase operation (FREE = 1).

17.2.5 COMPARATOR OUTPUT POLARITY

Inverting the output of the comparator is functionally equivalent to swapping the comparator inputs. The polarity of the comparator output can be inverted by setting the CxPOL bit of the CMxCON0 register. Clearing the CxPOL bit results in a non-inverted output.

Table 17-2 shows the output state versus input conditions, including polarity control.

TABLE 17-2: COMPARATOR OUTPUT STATE VS. INPUT CONDITIONS

Input Condition	CxPOL	CxOUT
$CxV_N > CxV_P$	0	0
$CxV_N < CxV_P$	0	1
$CxV_N > CxV_P$	1	1
$CxV_N < CxV_P$	1	0

17.2.6 COMPARATOR SPEED/POWER SELECTION

The trade-off between speed or power can be optimized during program execution with the CxSP control bit. The default state for this bit is ‘1’ which selects the Normal-Speed mode. Device power consumption can be optimized at the cost of slower comparator propagation delay by clearing the CxSP bit to ‘0’.

17.3 Analog Input Connection Considerations

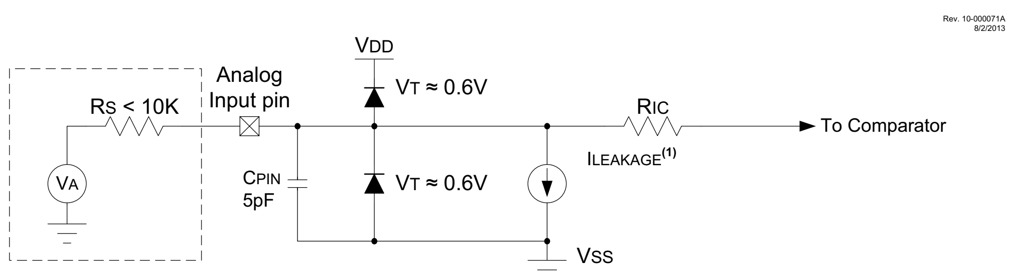
A simplified circuit for an analog input is shown in Figure 17-3. Since the analog input pins share their connection with a digital input, they have reverse biased ESD protection diodes to V_{DD} and V_{SS}. The analog input, therefore, must be between V_{SS} and V_{DD}. If the input voltage deviates from this range by more than 0.6V in either direction, one of the diodes is forward biased and a latch-up may occur.

A maximum source impedance of 10 kΩ is recommended for the analog sources. Also, any external component connected to an analog input pin, such as a capacitor or a Zener diode, should have very little leakage current to minimize inaccuracies introduced.

Note 1: When reading a PORT register, all pins configured as analog inputs will read as a ‘0’. Pins configured as digital inputs will convert as an analog input, according to the input specification.

2: Analog levels on any pin defined as a digital input, may cause the input buffer to consume more current than is specified.

FIGURE 17-3: ANALOG INPUT MODEL



Legend:
C_{PIN} = Input Capacitance
$I_{LEAKAGE}$ = Leakage Current at the pin due to various junctions
R_{IC} = Interconnect Resistance
R_S = Source Impedance
V_A = Analog Voltage
V_T = Threshold Voltage

Note 1: See **Section 29.0 “Electrical Specifications”**.

REGISTER 17-2: CMxCON1: COMPARATOR Cx CONTROL REGISTER 1

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	R/W-0/0	R/W-0/0	R/W-0/0
CxINTP	CxINTN	CxPCH<1:0>		—	CxNCH<2:0>		
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **CxINTP:** Comparator Interrupt on Positive Going Edge Enable bits
1 = The CxIF interrupt flag will be set upon a positive going edge of the CxOUT bit
0 = No interrupt flag will be set on a positive going edge of the CxOUT bit

bit 6 **CxINTN:** Comparator Interrupt on Negative Going Edge Enable bits
1 = The CxIF interrupt flag will be set upon a negative going edge of the CxOUT bit
0 = No interrupt flag will be set on a negative going edge of the CxOUT bit

bit 5-4 **CxPCH<1:0>:** Comparator Positive Input Channel Select bits
11 = CxVP connects to VSS
10 = CxVP connects to FVR Voltage Reference
01 = CxVP connects to DAC Voltage Reference
00 = CxVP connects to CxIN+ pin

bit 3 **Unimplemented:** Read as ‘0’

bit 2-0 **CxNCH<2:0>:** Comparator Negative Input Channel Select bits
111 = Reserved
110 = Reserved
101 = Reserved
100 = CxVN connects to FVR Voltage reference
011 = CxVN connects to CxIN3- pin
010 = CxVN connects to CxIN2- pin
001 = CxVN connects to CxIN1- pin
000 = CxVN connects to CxIN0- pin

REGISTER 17-3: CMOUT: COMPARATOR OUTPUT REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	R-0/0	R-0/0
—	—	—	—	—	—	MC2OUT	MC1OUT
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-2 **Unimplemented:** Read as ‘0’

bit 1 **MC2OUT:** Mirror Copy of C2OUT bit

bit 0 **MC1OUT:** Mirror Copy of C1OUT bit

21.2.4 SPI SLAVE MODE

In Slave mode, the data is transmitted and received as external clock pulses appear on SCKx. When the last bit is latched, the SSPxIF interrupt flag bit is set.

Before enabling the module in SPI Slave mode, the clock line must match the proper Idle state. The clock line can be observed by reading the SCKx pin. The Idle state is determined by the CKP bit of the SSPxCON1 register.

While in Slave mode, the external clock is supplied by the external clock source on the SCKx pin. This external clock must meet the minimum high and low times as specified in the electrical specifications.

While in Sleep mode, the slave can transmit/receive data. The shift register is clocked from the SCKx pin input and when a byte is received, the device will generate an interrupt. If enabled, the device will wake-up from Sleep.

21.2.4.1 Daisy-Chain Configuration

The SPI bus can sometimes be connected in a daisy-chain configuration. The first slave output is connected to the second slave input, the second slave output is connected to the third slave input, and so on. The final slave output is connected to the master input. Each slave sends out, during a second group of clock pulses, an exact copy of what was received during the first group of clock pulses. The whole chain acts as one large communication shift register. The daisy-chain feature only requires a single Slave Select line from the master device.

Figure 21-7 shows the block diagram of a typical daisy-chain connection when operating in SPI mode.

In a daisy-chain configuration, only the most recent byte on the bus is required by the slave. Setting the BOEN bit of the SSPxCON3 register will enable writes to the SSPxBUF register, even if the previous byte has not been read. This allows the software to ignore data that may not apply to it.

21.2.5 SLAVE SELECT SYNCHRONIZATION

The Slave Select can also be used to synchronize communication. The Slave Select line is held high until the master device is ready to communicate. When the Slave Select line is pulled low, the slave knows that a new transmission is starting.

If the slave fails to receive the communication properly, it will be reset at the end of the transmission, when the Slave Select line returns to a high state. The slave is then ready to receive a new transmission when the Slave Select line is pulled low again. If the Slave Select line is not used, there is a risk that the slave will eventually become out of sync with the master. If the slave misses a bit, it will always be one bit off in future transmissions. Use of the Slave Select line allows the slave and master to align themselves at the beginning of each transmission.

The $\overline{\text{SSx}}$ pin allows a Synchronous Slave mode. The SPI must be in Slave mode with $\overline{\text{SSx}}$ pin control enabled (SSPxCON1<3:0> = `0100`).

When the $\overline{\text{SSx}}$ pin is low, transmission and reception are enabled and the SDOx pin is driven.

When the $\overline{\text{SSx}}$ pin goes high, the SDOx pin is no longer driven, even if in the middle of a transmitted byte and becomes a floating output. External pull-up/pull-down resistors may be desirable depending on the application.

> **Note 1:** When the SPI is in Slave mode with $\overline{\text{SSx}}$ pin control enabled (SSPxCON1<3:0> = `0100`), the SPI module will reset if the $\overline{\text{SSx}}$ pin is set to VDD.
>
> **2:** When the SPI is used in Slave mode with CKE set; the user must enable $\overline{\text{SSx}}$ pin control.
>
> **3:** While operated in SPI Slave mode the SMP bit of the SSPxSTAT register must remain clear.

When the SPI module resets, the bit counter is forced to '`0`'. This can be done by either forcing the $\overline{\text{SSx}}$ pin to a high level or clearing the SSPEN bit.

21.5.4 SLAVE MODE 10-BIT ADDRESS RECEPTION

This section describes a standard sequence of events for the MSSP module configured as an I²C slave in 10-bit Addressing mode.

Figure 21-20 is used as a visual reference for this description.

This is a step by step process of what must be done by slave software to accomplish I²C communication.

1. Bus starts idle.
2. Master sends Start condition; S bit of SSPxSTAT is set; SSPxIF is set if interrupt on Start detect is enabled.
3. Master sends matching high address with R/$\overline{W}$ bit clear; UA bit of the SSPxSTAT register is set.
4. Slave sends $\overline{ACK}$ and SSPxIF is set.
5. Software clears the SSPxIF bit.
6. Software reads received address from SSPxBUF clearing the BF flag.
7. Slave loads low address into SSPxADD, releasing SCLx.
8. Master sends matching low address byte to the slave; UA bit is set.

> **Note:** Updates to the SSPxADD register are not allowed until after the $\overline{ACK}$ sequence.

9. Slave sends $\overline{ACK}$ and SSPxIF is set.

> **Note:** If the low address does not match, SSPxIF and UA are still set so that the slave software can set SSPxADD back to the high address. BF is not set because there is no match. CKP is unaffected.

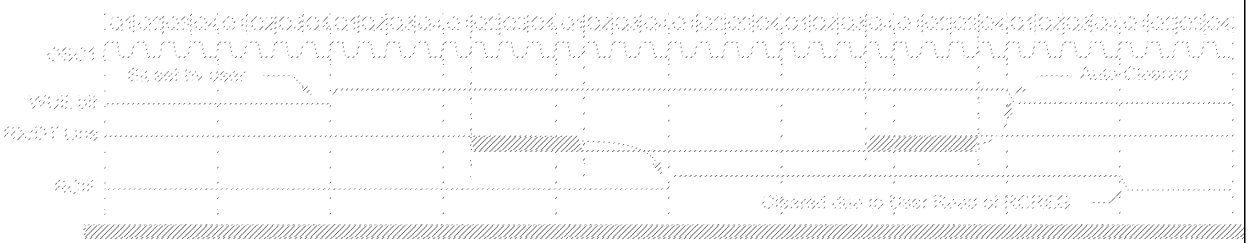
10. Slave clears SSPxIF.
11. Slave reads the received matching address from SSPxBUF clearing BF.
12. Slave loads high address into SSPxADD.
13. Master clocks a data byte to the slave and clocks out the slaves $\overline{ACK}$ on the ninth SCLx pulse; SSPxIF is set.
14. If SEN bit of SSPxCON2 is set, CKP is cleared by hardware and the clock is stretched.
15. Slave clears SSPxIF.
16. Slave reads the received byte from SSPxBUF clearing BF.
17. If SEN is set the slave sets CKP to release the SCLx.
18. Steps 13-17 repeat for each received byte.
19. Master sends Stop to end the transmission.

21.5.5 10-BIT ADDRESSING WITH ADDRESS OR DATA HOLD

Reception using 10-bit addressing with AHEN or DHEN set is the same as with 7-bit modes. The only difference is the need to update the SSPxADD register using the UA bit. All functionality, specifically when the CKP bit is cleared and SCLx line is held low are the same. Figure 21-21 can be used as a reference of a slave in 10-bit addressing with AHEN set.

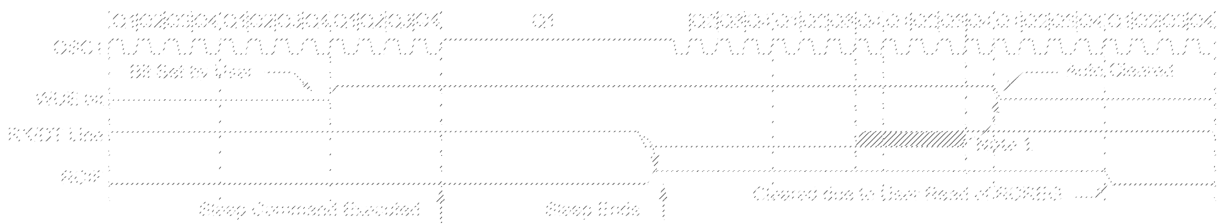
Figure 21-22 shows a standard waveform for a slave transmitter in 10-bit Addressing mode.

FIGURE 22-7: AUTO-WAKE-UP BIT (WUE) TIMING DURING NORMAL OPERATION



Note 1: The EUSART remains in Idle while the WUE bit is set.

FIGURE 22-8: AUTO-WAKE-UP BIT (WUE) TIMINGS DURING SLEEP



Note 1: If the wake-up event requires long oscillator warm-up time, the automatic clearing of the WUE bit can occur while the stposc signal is still active. This sequence should not depend on the presence of Q clocks.

2: The EUSART remains in Idle while the WUE bit is set.

22.4.4 BREAK CHARACTER SEQUENCE

The EUSART module has the capability of sending the special Break character sequences that are required by the LIN bus standard. A Break character consists of a Start bit, followed by 12 ‘0’ bits and a Stop bit.

To send a Break character, set the SENDB and TXEN bits of the TXSTA register. The Break character transmission is then initiated by a write to the TXREG. The value of data written to TXREG will be ignored and all ‘0’s will be transmitted.

The SENDB bit is automatically reset by hardware after the corresponding Stop bit is sent. This allows the user to preload the transmit FIFO with the next transmit byte following the Break character (typically, the Sync character in the LIN specification).

The TRMT bit of the TXSTA register indicates when the transmit operation is active or idle, just as it does during normal transmission. See Figure 22-9 for the timing of the Break character sequence.

22.4.4.1 Break and Sync Transmit Sequence

The following sequence will start a message frame header made up of a Break, followed by an auto-baud Sync byte. This sequence is typical of a LIN bus master.

1. Configure the EUSART for the desired mode.
2. Set the TXEN and SENDB bits to enable the Break sequence.
3. Load the TXREG with a dummy character to initiate transmission (the value is ignored).
4. Write ‘55h’ to TXREG to load the Sync character into the transmit FIFO buffer.
5. After the Break has been sent, the SENDB bit is reset by hardware and the Sync character is then transmitted.

When the TXREG becomes empty, as indicated by the TXIF, the next data byte can be written to TXREG.

22.4.5 RECEIVING A BREAK CHARACTER

The Enhanced EUSART module can receive a Break character in two ways.

The first method to detect a Break character uses the FERR bit of the RCSTA register and the received data as indicated by RCREG. The Baud Rate Generator is assumed to have been initialized to the expected baud rate.

A Break character has been received when;

- RCIF bit is set
- FERR bit is set
- RCREG = 00h

The second method uses the Auto-Wake-up feature described in **Section22.4.3 “Auto-Wake-up on Break”**. By enabling this feature, the EUSART will sample the next two transitions on RX/DT, cause an RCIF interrupt, and receive the next data byte followed by another interrupt.

Note that following a Break character, the user will typically want to enable the Auto-Baud Detect feature. For both methods, the user can set the ABDEN bit of the BAUDCON register before placing the EUSART in Sleep mode.

FIGURE 22-9: SEND BREAK CHARACTER SEQUENCE

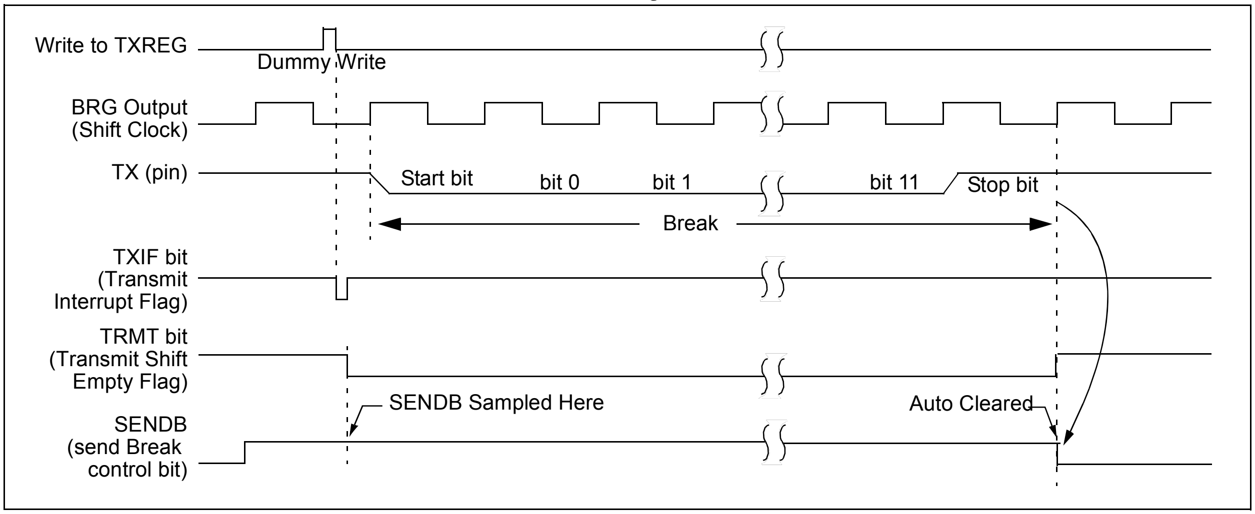


TABLE 24-3: SUMMARY OF REGISTERS ASSOCIATED WITH CLCx

Name	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	Register on Page
ANSELA	—	—	—	ANSA4	—	ANSA2	ANSA1	ANSA0	110
ANSELB	—	—	ANSB5	ANSB4	—	—	—	—	114
ANSELC	ANSC7	ANSC6	—	—	ANSC3	ANSC2	ANSC1	ANSC0	118
CLC1CON	LC1EN	LC1OE	LC1OUT	LC1INTP	LC1INTN	LC1MODE<2:0>			263
CLCDATA	—	—	—	—	—	MLC3OUT	MLC2OUT	MLC1OUT	271
CLC1GLS0	LC1G1D4T	LC1G1D4N	LC1G1D3T	LC1G1D3N	LC1G1D2T	LC1G1D2N	LC1G1D1T	LC1G1D1N	267
CLC1GLS1	LC1G2D4T	LC1G2D4N	LC1G2D3T	LC1G2D3N	LC1G2D2T	LC1G2D2N	LC1G2D1T	LC1G2D1N	268
CLC1GLS2	LC1G3D4T	LC1G3D4N	LC1G3D3T	LC1G3D3N	LC1G3D2T	LC1G3D2N	LC1G3D1T	LC1G3D1N	269
CLC1GLS3	LC1G4D4T	LC1G4D4N	LC1G4D3T	LC1G4D3N	LC1G4D2T	LC1G4D2N	LC1G4D1T	LC1G4D1N	270
CLC1POL	LC1POL	—	—	—	LC1G4POL	LC1G3POL	LC1G2POL	LC1G1POL	264
CLC1SEL0	—	LC1D2S<2:0>			—	LC1D1S<2:0>			265
CLC1SEL1	—	LC1D4S<2:0>			—	LC1D3S<2:0>			266
CLC2CON	LC2EN	LC2OE	LC2OUT	LC2INTP	LC2INTN	LC2MODE<2:0>			263
CLC2GLS0	LC2G1D4T	LC2G1D4N	LC2G1D3T	LC2G1D3N	LC2G1D2T	LC2G1D2N	LC2G1D1T	LC2G1D1N	267
CLC2GLS1	LC2G2D4T	LC2G2D4N	LC2G2D3T	LC2G2D3N	LC2G2D2T	LC2G2D2N	LC2G2D1T	LC2G2D1N	268
CLC2GLS2	LC2G3D4T	LC2G3D4N	LC2G3D3T	LC2G3D3N	LC2G3D2T	LC2G3D2N	LC2G3D1T	LC2G3D1N	269
CLC2GLS3	LC2G4D4T	LC2G4D4N	LC2G4D3T	LC2G4D3N	LC2G4D2T	LC2G4D2N	LC2G4D1T	LC2G4D1N	270
CLC2POL	LC2POL	—	—	—	LC2G4POL	LC2G3POL	LC2G2POL	LC2G1POL	264
CLC2SEL0	—	LC2D2S<2:0>			—	LC2D1S<2:0>			265
CLC2SEL1	—	LC2D4S<2:0>			—	LC2D3S<2:0>			266
CLC3CON	LC3EN	LC3OE	LC3OUT	LC3INTP	LC3INTN	LC3MODE<2:0>			263
CLC3GLS0	LC3G1D4T	LC3G1D4N	LC3G1D3T	LC3G1D3N	LC3G1D2T	LC3G1D2N	LC3G1D1T	LC3G1D1N	267
CLC3GLS1	LC3G2D4T	LC3G2D4N	LC3G2D3T	LC3G2D3N	LC3G2D2T	LC3G2D2N	LC3G2D1T	LC3G2D1N	268
CLC3GLS2	LC3G3D4T	LC3G3D4N	LC3G3D3T	LC3G3D3N	LC3G3D2T	LC3G3D2N	LC3G3D1T	LC3G3D1N	269
CLC3GLS3	LC3G4D4T	LC3G4D4N	LC3G4D3T	LC3G4D3N	LC3G4D2T	LC3G4D2N	LC3G4D1T	LC3G4D1N	270
CLC3POL	LC3POL	—	—	—	LC3G4POL	LC3G3POL	LC3G2POL	LC3G1POL	264
CLC3SEL0	—	LC3D2S<2:0>			—	LC3D1S<2:0>			265
CLC3SEL1	—	LC3D4S<2:0>			—	LC3D3S<2:0>			266
CLC4CON	LC4EN	LC4OE	LC4OUT	LC4INTP	LC4INTN	LC4MODE<2:0>			263
CLC4GLS0	LC4G1D4T	LC4G1D4N	LC4G1D3T	LC4G1D3N	LC4G1D2T	LC4G1D2N	LC4G1D1T	LC4G1D1N	267
CLC4GLS1	LC4G2D4T	LC4G2D4N	LC4G2D3T	LC4G2D3N	LC4G2D2T	LC4G2D2N	LC4G2D1T	LC4G2D1N	268
CLC4GLS2	LC4G3D4T	LC4G3D4N	LC4G3D3T	LC4G3D3N	LC4G3D2T	LC4G3D2N	LC4G3D1T	LC4G3D1N	269
CLC4GLS3	LC4G4D4T	LC4G4D4N	LC4G4D3T	LC4G4D3N	LC4G4D2T	LC4G4D2N	LC4G4D1T	LC4G4D1N	270
CLC4POL	LC4POL	—	—	—	LC4G4POL	LC4G3POL	LC4G2POL	LC4G1POL	264
CLC4SEL0	—	LC4D2S<2:0>			—	LC4D1S<2:0>			265
CLC4SEL1	—	LC4D4S<2:0>			—	LC4D3S<2:0>			266
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	75
PIE3	—	—	—	—	CLC4IE	CLC3IE	CLC2IE	CLC1IE	78
PIR3	—	—	—	—	CLC4IF	CLC3IF	CLC2IF	CLC1IF	81
TRISA	—	—	TRISA5	TRISA4	—(1)	TRISA2	TRISA1	TRISA0	109
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	—	—	—	—	113
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	117

Legend: — = unimplemented read as '0',. Shaded cells are not used for CLC module.
Note 1: Unimplemented, read as '1'.

REGISTER 25-3: NCOxACCL: NCOx ACCUMULATOR REGISTER – LOW BYTE

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
NCOxACC<7:0>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **NCOxACC<7:0>:** NCOx Accumulator, Low Byte

REGISTER 25-4: NCOxACCH: NCOx ACCUMULATOR REGISTER – HIGH BYTE

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
NCOxACC<15:8>							
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-0 **NCOxACC<15:8>:** NCOx Accumulator, High Byte

REGISTER 25-5: NCOxACCU: NCOx ACCUMULATOR REGISTER – UPPER BYTE

U-0	U-0	U-0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
—	—	—	—	NCOxACC<19:16>			
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-4 **Unimplemented:** Read as ‘0’

bit 3-0 **NCOxACC<19:16>:** NCOx Accumulator, Upper Byte

FIGURE 26-5: SHUTDOWN FUNCTIONALITY, AUTO-RESTART DISABLED (GxARSEN = 0, GxASDLA = 01, GxASDLB = 01)

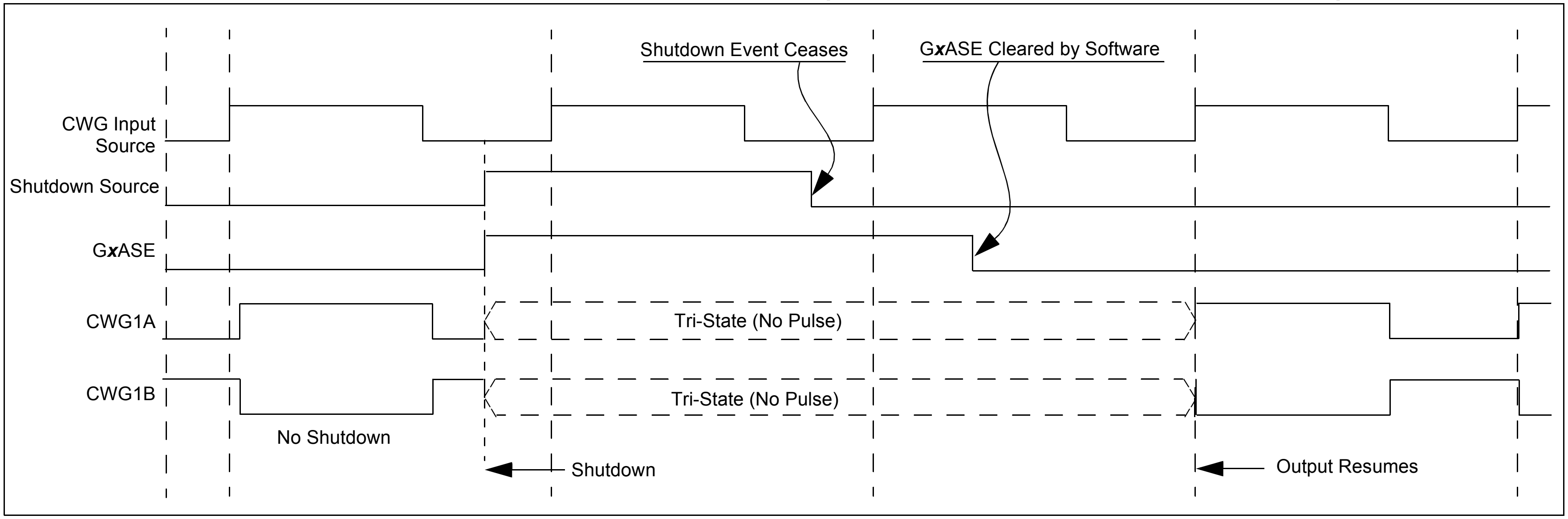
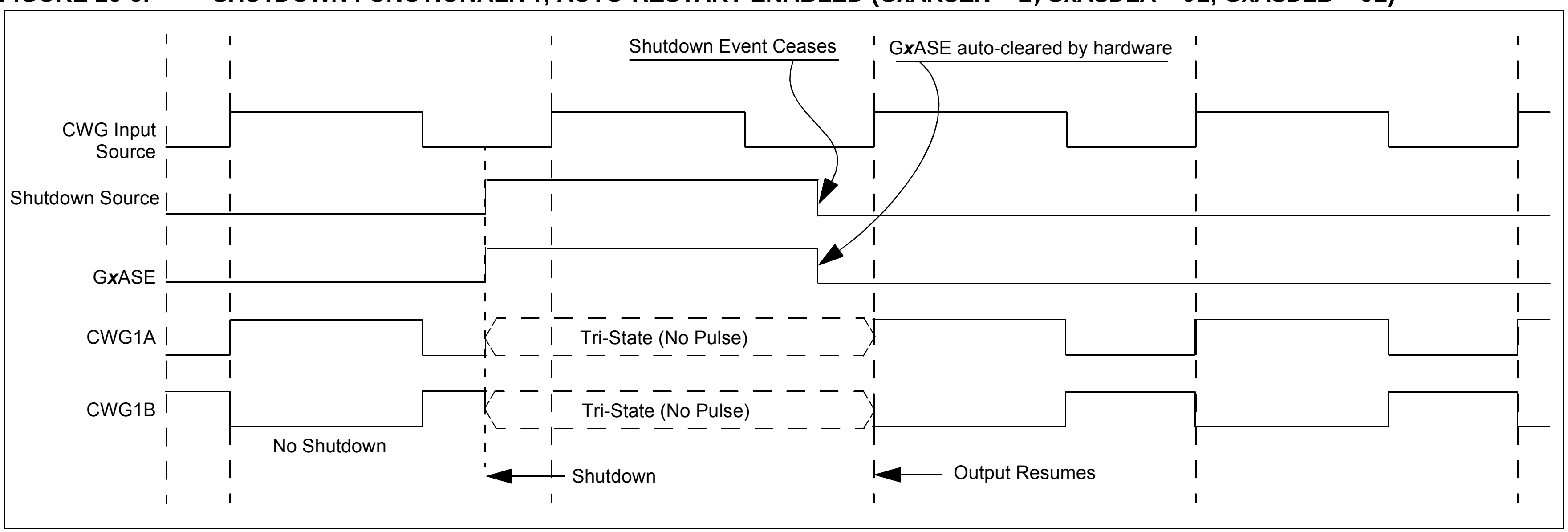


FIGURE 26-6: SHUTDOWN FUNCTIONALITY, AUTO-RESTART ENABLED (GxARSEN = 1, GxASDLA = 01, GxASDLB = 01)



29.0 ELECTRICAL SPECIFICATIONS

29.1 Absolute Maximum Ratings(†)

Ambient temperature under bias .... -40°C to +125°C
Storage temperature .... -65°C to +150°C
Voltage on pins with respect to VSS
  on VDD pin
    PIC16F1508/9 .... -0.3V to +6.5V
    PIC16LF1508/9 .... -0.3V to +4.0V
  on $\overline{MCLR}$ pin .... -0.3V to +9.0V
  on all other pins .... -0.3V to (VDD + 0.3V)
Maximum current
  on VSS pin(1)
    -40°C ≤ TA ≤ +85°C .... 250 mA
    +85°C ≤ TA ≤ +125°C .... 85 mA
  on VDD pin(1)
    -40°C ≤ TA ≤ +85°C .... 250 mA
    +85°C ≤ TA ≤ +125°C .... 85 mA
  Sunk by any standard I/O pin .... 50 mA
  Sourced by any standard I/O pin .... 50 mA
Clamp current, IK (VPIN < 0 or VPIN > VDD) .... ±20 mA
Total power dissipation(2) .... 800 mW

Note 1: Maximum current rating requires even load distribution across I/O pins. Maximum current rating may be limited by the device package power dissipation characterizations, see Table 29-6 to calculate device specifications.

2: Power dissipation is calculated as follows: $P_{DIS} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum(V_{OI} \times I_{OL})$.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure above maximum rating conditions for extended periods may affect device reliability.

FIGURE 30-25: IDD TYPICAL, HFINTOSC, PIC16F1508/9 ONLY

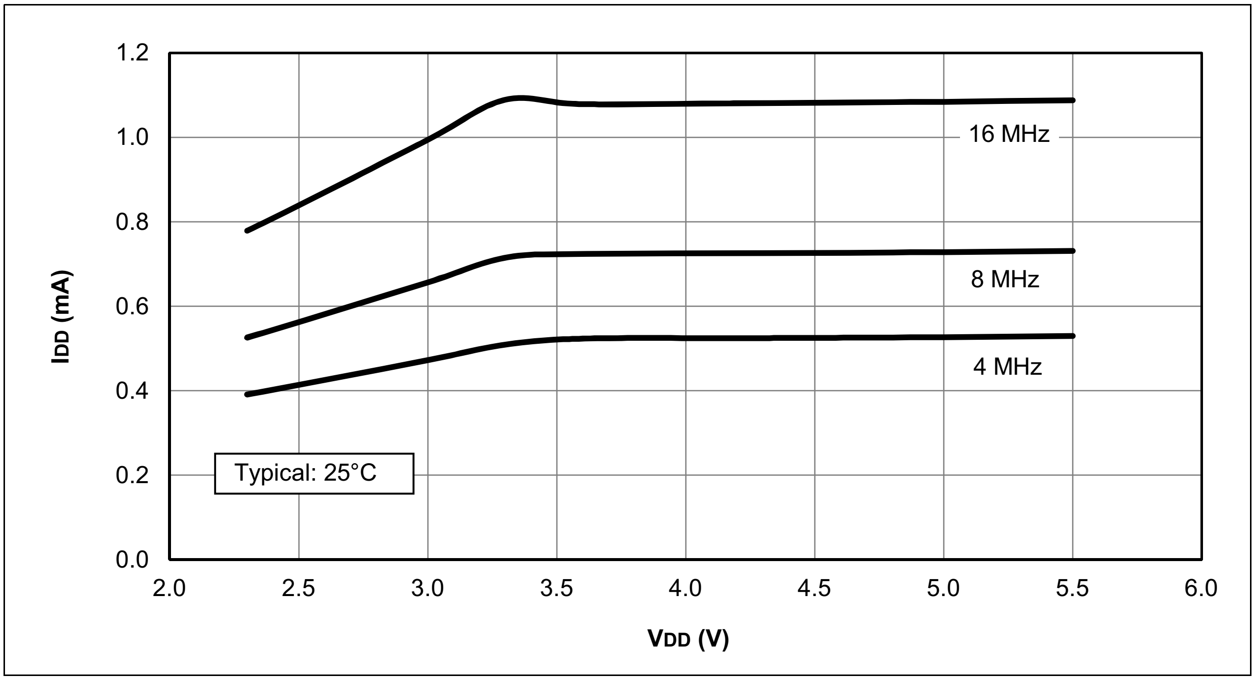
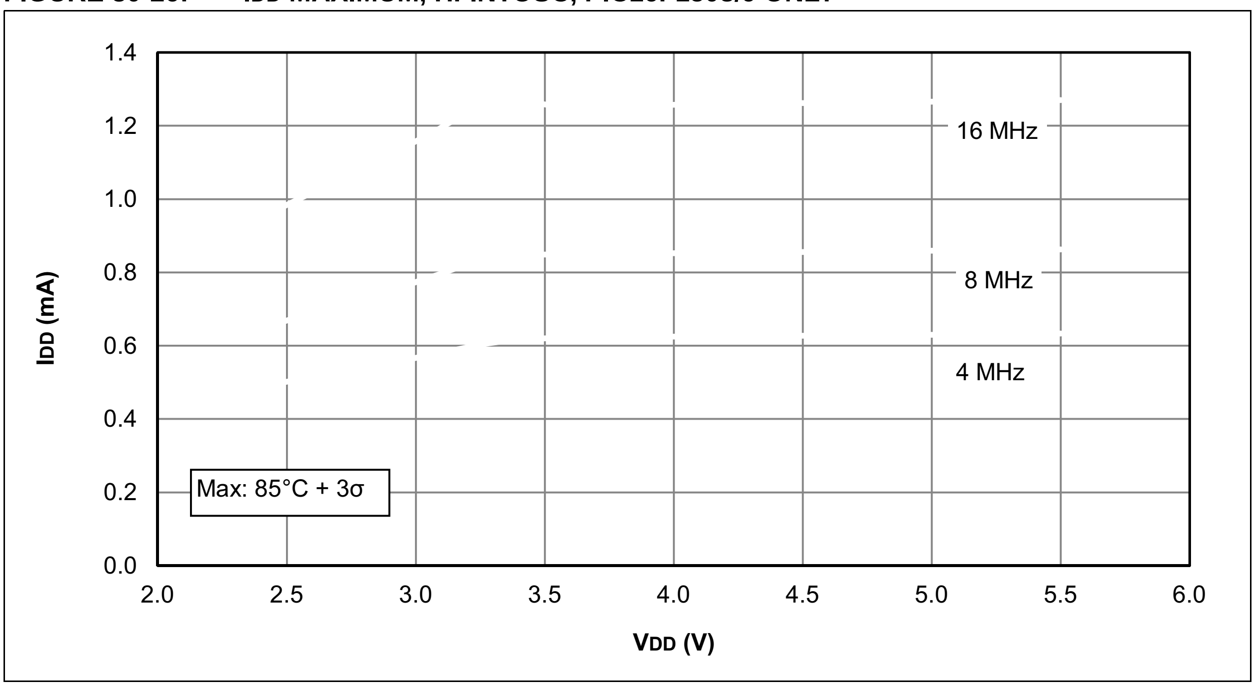


FIGURE 30-26: IDD MAXIMUM, HFINTOSC, PIC16F1508/9 ONLY



31.6 MPLAB X SIM Software Simulator

The MPLAB X SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB X SIM Software Simulator fully supports symbolic debugging using the MPLAB XC Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

31.7 MPLAB REAL ICE In-Circuit Emulator System

The MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs all 8, 16 and 32-bit MCU, and DSC devices with the easy-to-use, powerful graphical user interface of the MPLAB X IDE.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ-11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB X IDE. MPLAB REAL ICE offers significant advantages over competitive emulators including full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, logic probes, a ruggedized probe interface and long (up to three meters) interconnection cables.

31.8 MPLAB ICD 3 In-Circuit Debugger System

The MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost-effective, high-speed hardware debugger/programmer for Microchip Flash DSC and MCU devices. It debugs and programs PIC Flash microcontrollers and dsPIC DSCs with the powerful, yet easy-to-use graphical user interface of the MPLAB IDE.

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

31.9 PICkit 3 In-Circuit Debugger/ Programmer

The MPLAB PICkit 3 allows debugging and programming of PIC and dsPIC Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB IDE. The MPLAB PICkit 3 is connected to the design engineer's PC using a full-speed USB interface and can be connected to the target via a Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the Reset line to implement in-circuit debugging and In-Circuit Serial Programming™ (ICSP™).

31.10 MPLAB PM3 Device Programmer

The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at V_{DDMIN} and V_{DDMAX} for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages, and a modular, detachable socket assembly to support various package types. The ICSP cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PIC devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices, and incorporates an MMC card for file storage and data applications.

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	[X][(1)]	-	X	/XX	XXX
Device	Tape and Reel Option		Temperature Range	Package	Pattern

Device:	PIC16LF1508, PIC16F1508, PIC16LF1509, PIC16F1509
Tape and Reel Option:	Blank = Standard packaging (tube or tray) T = Tape and Reel[(1)]
Temperature Range:	I = -40°C to +85°C (Industrial) E = -40°C to +125°C (Extended)
Package:[(2)]	GZ = UQFN ML = QFN P = Plastic DIP SO = SOIC SS = SSOP
Pattern:	QTP, SQTP, Code or Special Requirements (blank otherwise)

Examples:

a) PIC16LF1508T - I/SO
Tape and Reel,
Industrial temperature,
SOIC package

b) PIC16F1509 - I/P
Industrial temperature
PDIP package

c) PIC16F1508 - E/ML 298
Extended temperature,
QFN package
QTP pattern #298

Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.

2: For other small form-factor package availability and marking information, please visit www.microchip.com/packaging or contact your local sales office.